

H5N2504DL, H5N2504DS

Silicon N Channel MOS FET High Speed Power Switching

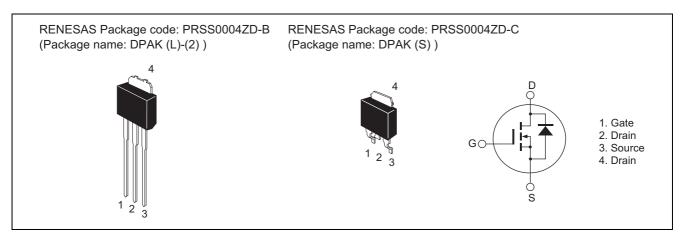
REJ03G1106-0200 (Previous: ADE-208-1375A)

> Rev.2.00 Sep 07, 2005

Features

- Low on-resistance
- Low leakage current
- High speed switching
- Low gate charge
- Avalanche ratings

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V _{DSS}	250	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I _D	7	A
Drain peak current	I _{D (pulse)} Note 1	28	A
Body-drain diode reverse drain current	I _{DR}	7	A
Body-drain diode reverse drain peak current	I _{DR (pulse)} Note 1	28	A
Avalanche current	I _{AP} Note 3	7	А
Channel dissipation	Pch Note 2	30	W
Channel to case thermal Impedance	θ ch-c	4.17	°C/W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. Value at Tc = 25°C

3. Tch ≤ 150°C

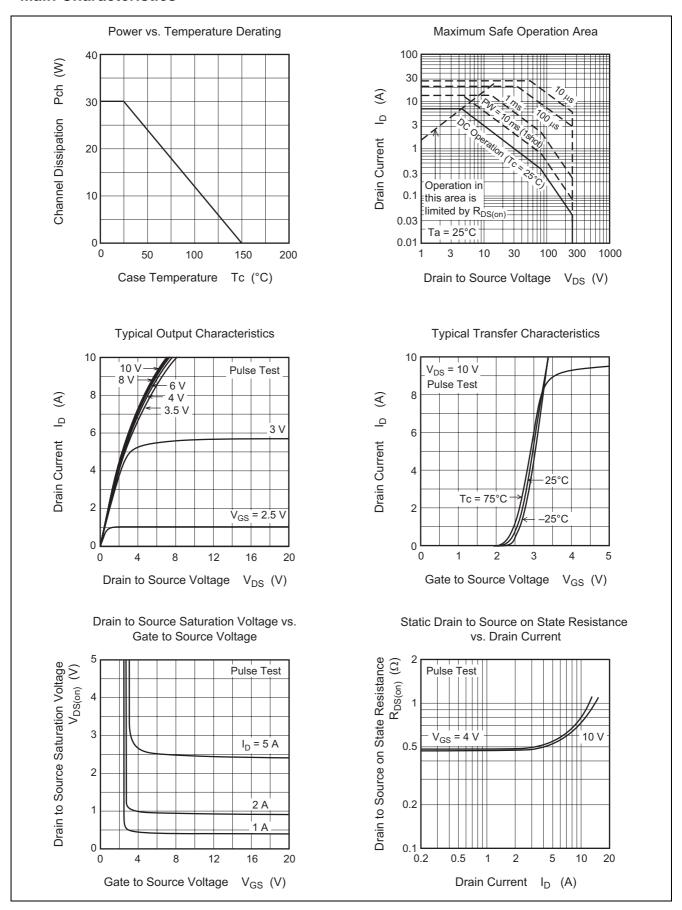
Electrical Characteristics

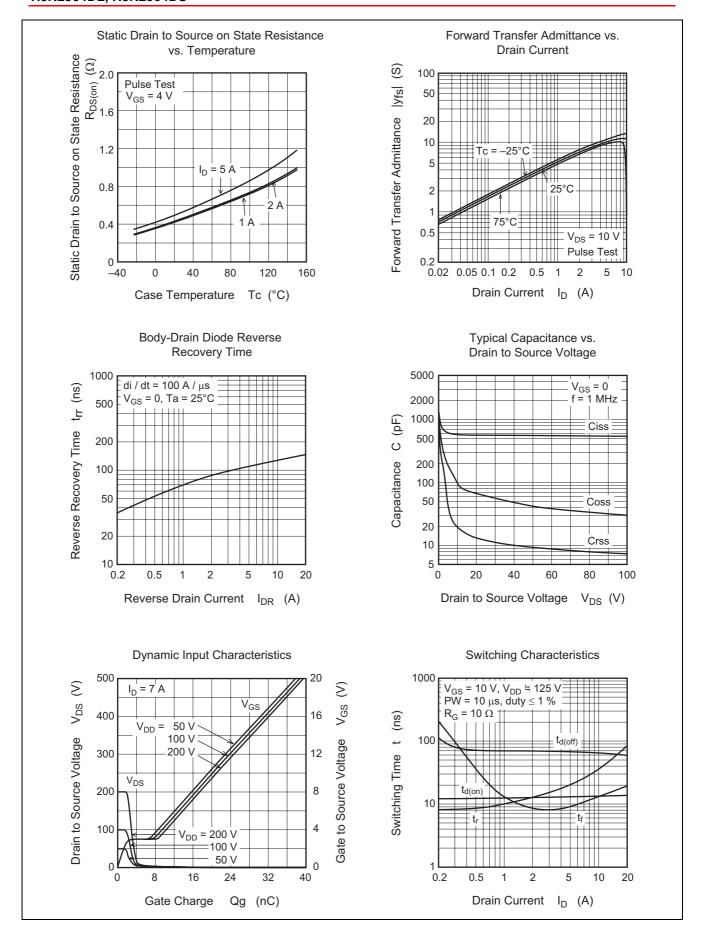
 $(Ta = 25^{\circ}C)$

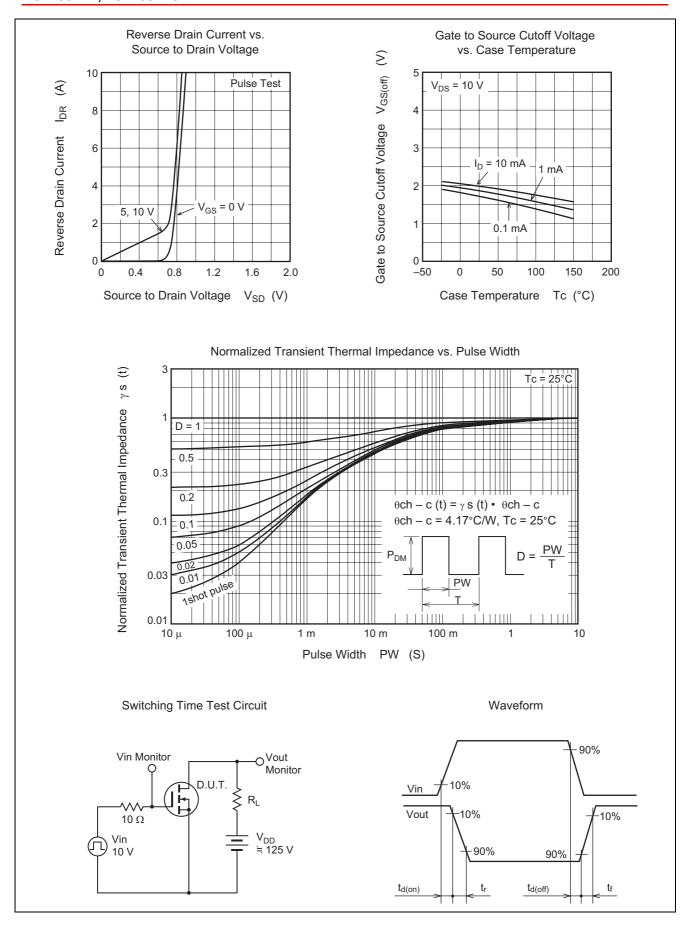
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	250	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}		_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	1	μΑ	$V_{DS} = 250 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	1.0	_	2.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}		0.48	0.63	Ω	$I_D = 3.5 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 4}}$
	R _{DS (on)}	_	0.5	0.67	Ω	$I_D = 3.5 \text{ A}, V_{GS} = 4 \text{ V}^{\text{Note 4}}$
Forward transfer admittance	y _{fs}	5	8.5		S	$I_D = 3.5 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 4}}$
Input capacitance	Ciss	_	570	_	pF	V _{DS} = 25 V
Output capacitance	Coss	_	60	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	12	_	pF	f = 1 MHz
Turn-on delay time	t _{d (on)}	_	13	_	ns	I _D = 3.5 A
Rise time	t _r	_	18	_	ns	V _{GS} = 10 V
Turn-off delay time	t _{d (off)}	_	70	_	ns	$R_L = 35.7 \Omega$
Fall time	t _f	_	8	_	ns	$Rg = 10 \Omega$
Total gate charge	Qg	_	21	_	nC	V _{DD} = 200 V
Gate to source charge	Qgs	_	2	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	6	_	nC	$I_D = 7 A$
Body-drain diode forward voltage	V_{DF}	_	0.85	1.30	V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery time	t _{rr}	_	120	_	ns	$I_F = 7 \text{ A}, V_{GS} = 0$
Body-drain diode reverse recovery charge	Q _{rr}	_	0.48	_	μС	di _F /dt = 100 A/μs

Note: 4. Pulse test

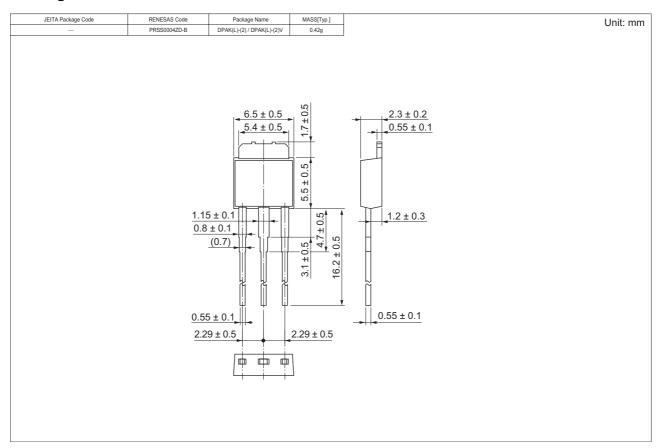
Main Characteristics

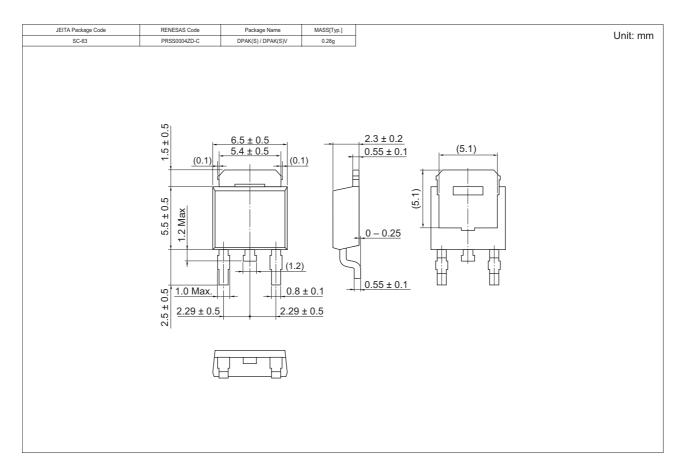






Package Dimensions





Ordering Information

Part Name	Quantity	Shipping Container
H5N2504DL-E	3200 pcs	Box (Sack)
H5N2504DSTL-E	3000 pcs	Taping

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